



#### Analysis of Hot Spots in Crystalline Silicon Modules and their Impact on Roof Structures



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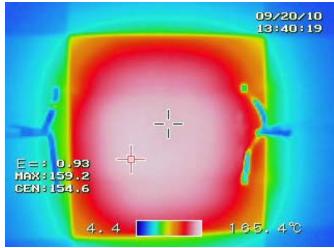


## Introduction

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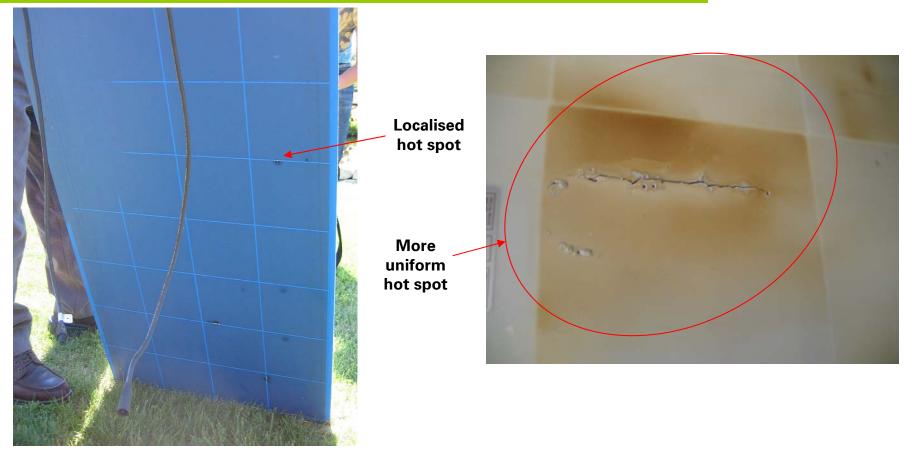
- What are hot spots? What the standards say:
- **IEC definition:** "Hot-spot heating occurs in a module when its operating current exceeds the reduced short-circuit current of a shadowed cell or group of cells within it"
- **UL definition:** "This reduced short-circuit current capability can be the result of a variety of causes including:
  - non-uniform illumination of the module (local shadowing)
  - individual cell degradation due to cracking
  - ..or loss of a portion of a series-parallel circuit due to individual interconnect open circuits."
- These hot spot mechanisms are the result of reverse biasing of cells which can lead to localized p-n junction breakdown
- Not all hot spots are the results of the p-n junction effect





### Example: By pass diode failure

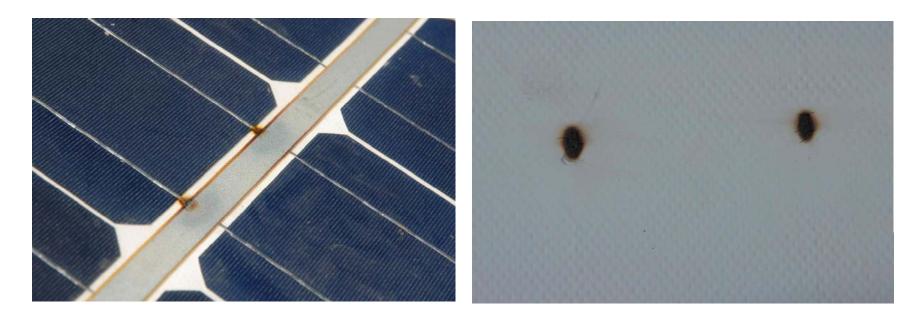




- Loss of protection from a faulty by pass diode during periods of shading can lead to hot spots
- The highest temperature occurs where current density is highest. This can produce non uniform heating
- Cell shunt resistance influences hot spot formation on shading. Shunt limits have increased as a result

# Example: Non cell hot spots

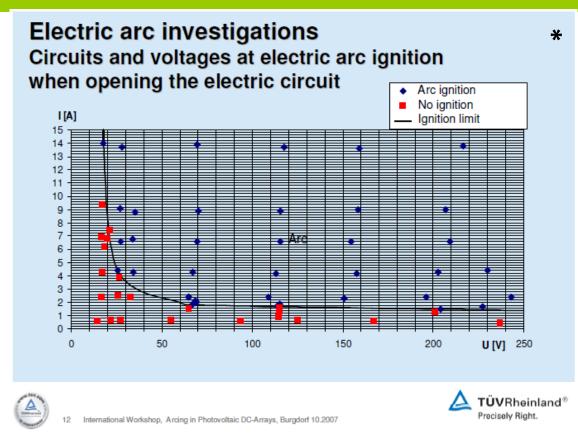




- Resistive heating is <u>not</u> associated with reverse bias conditions
- The heating is localized at the defect and can discolor the encapsulant and back sheet
- Poor workmanship can lead to soldering defects. These are not seen at the solar simulator
- The hot spot can be stable, does not increase in temperature
- In some cases, the contact will open

#### Arc effects





- DC arcs are another non reverse bias hot spot phenomenon
- Initiated under specific voltage/current conditions with a gap between conductors
- Current / Voltage ignition limits are well known
- The impact from this type of hot spot can be severe

\* Author acknowledges W Vassen of TUV Rhineland for permission to use the above chart

### Example: Structural interference





- Root cause is DC arc generation due to back sheet damage
- US systems: Negative ground needs single short
- EU systems: Typically need 2 shorts due to double isolation approach

#### Impact of roof structure proximity





- BIPV designs often require close proximity of the module to the roof structure
- The study performed between BP Solar and the Fraunhofer Institute was initiated to better understand and quantify the risks and behavior

# 2010 F-ISE/BP Solar hot spot study



#### • Scope of the study:

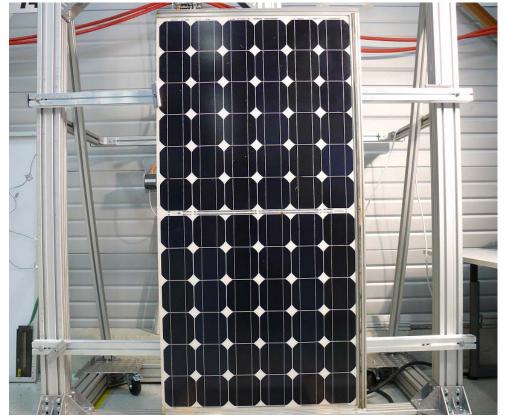
- Perform a statistical evaluation on a sample of modules exhibiting hot spots.
- Quantify the occurrence and temperature range/severity of hot spots

#### Characterization included

- Categorise the hot spots into specific root cause; cell contact, cell mismatch, cracked cell, etc
- Determine highest temperature for hot spots
- Perform electroluminescence and infra-red thermography
- Effect of thermal cycling & mechanical load on hot spots
- Heating influence on adjacent/close proximity structures with limited ventilation
- Evaluate effect of rear side module damage at high voltages

#### Module samples used in study





- BP Solar supplied 28 modules with varying degrees of hot spots
- Tests were performed at F-ISE, Freiburg
- Structures were custom built to replicate real field conditions
- Test protocols were followed according to IEC61215 & UL1703

# Hot spot characterization



- Full visual inspection, EL, & IR images was made on all modules
- Hot spot temperatures were measured under illumination (Class B-B-A solar simulator at 1000W/m<sup>2</sup>).
- Both lsc and Imp current condition were investigated
- Initial condition: Ambient temperature was 20°C and ventilation was not limited
- Table below shows the 5 highest hot spot temperatures found in the study

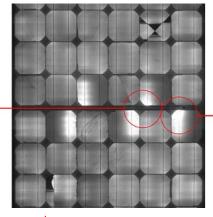
		Maximum hot spot temperature measured	
Sample	Isc (A)	T(C) @ lsc	T(C) @ Imp
A	4.9	301	144
В	5.1	312	267
С	5.0	272	147
D	4.9	296	210
E	4.6	287	172

# EL and IR images









T(MPP) = 91 °C T(SC) = 126 °C



T(SC) = 153 °C

T(MPP) = 110 °C

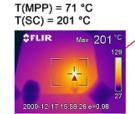
T(MPP) = 113 °C T(SC) = 164 °C

2009-12-17 15:67:59 e=0.98

Max 164°C

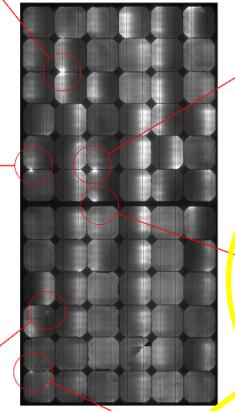
**\$FLIR** 

•Some broken cells were observed in module

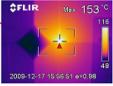


•The most serve hot spots observed in the group were from high resistance solder joints

Sample A



T(MPP) = 100 °C T(SC) = 153 °C





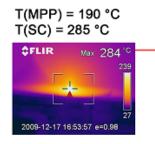
T(MPP) = 96 °C T(SC) = 137 °C



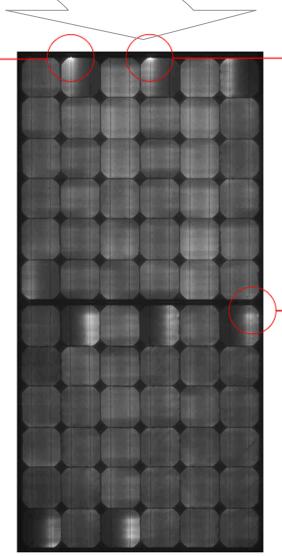
# EL and IR images continued







#### Sample B



T(MPP) = 267 °C T(SC) = 312 °C



T(MPP) = 69 °C T(SC) = 76 °C



## Hot spot with restricted ventilation



- Rear side of the module (samples A thru E) was closed off using a wooden panel
- Air gap: 38mm
- Ambient raised to 40°C with modules held at lsc
- Top 5 highest hot spot temperatures are shown below
- Temp trend was not consistent; 3 increased in temperature, 1 decreased, 1 unchanged
- Suggests that the hot spot source and properties can vary
- The module with the highest temperature hot spot was chosen for a "worse case" test
- This worse case test was designed to measure temperature rise in very proximity

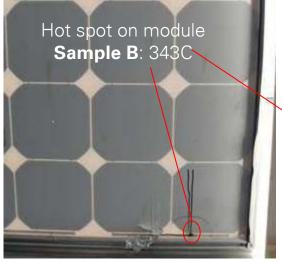
Maximum hot spot temperature measured			
Sample	lsc (A)	T(C) @ lsc	
A	5.2	300	Sample B
В	5.2	343	Cumpic B
С	5.2	283	
D	5.0	251	
E	4.7	332	

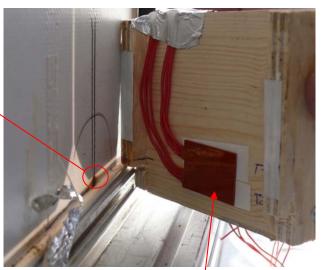
#### Worse case experiment Hot spot behavior in 10mm enclosure



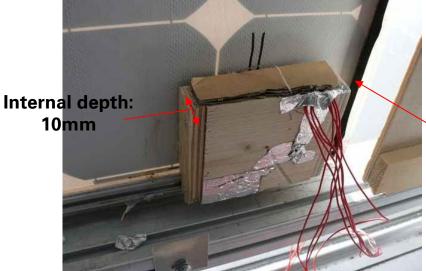


Back of module (Sample B) completely enclosed before start of test





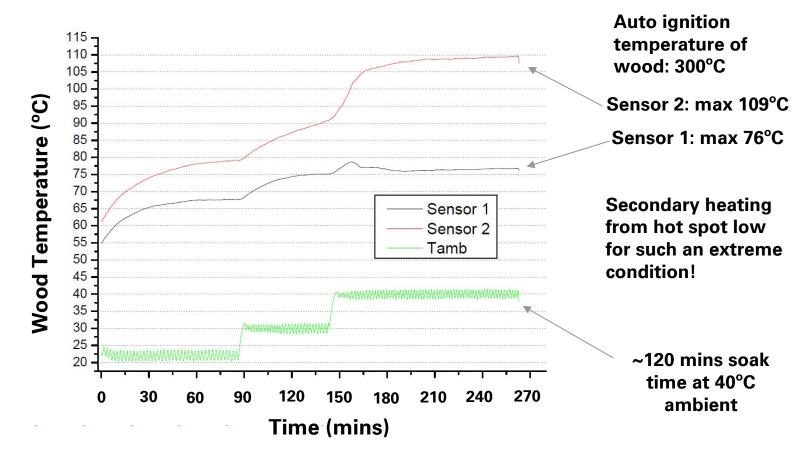
PT100 sensors



Enclosure to restrict air flow

# Max temp at 10mm from structure



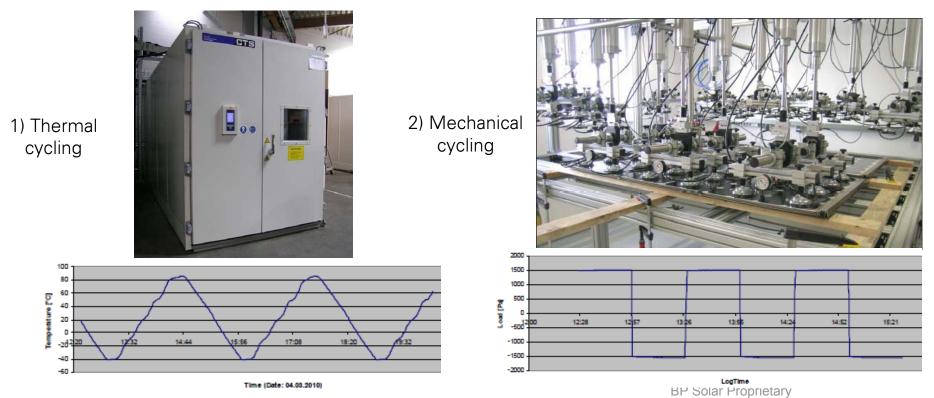


- Ambient temp stepped from 25°C to 40C° while module illuminated to produce lsc current
- Maximum temperature range at wood surface by end of test: 76°C to 109°C
- While absolute temperature of hot spot is high, the dissipated energy from it is very small
- This accounts for the relatively low temperatures of adjacent surfaces

#### **Thermal & mechanical loading**

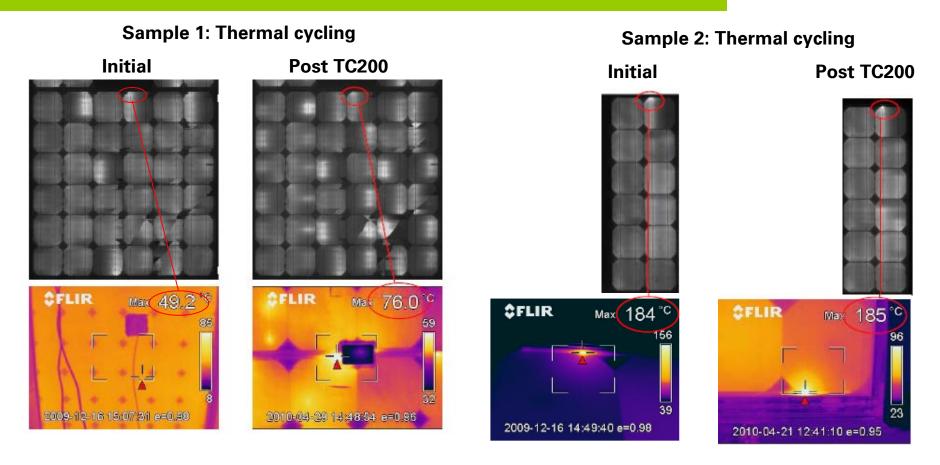


- As part of the study, the effect of thermal and mechanical cycling of hot spot propagation was investigated
- IEC 61215ed2, 10.11 and 10.6 (thermal & mechanical cycling respectively) procedures were followed
- Thermal cycling: -40°C to +85°C, 200 cycles
- Mechanical cycling: 2400Pa and 1500Pa, cycling front & rear, 1 hour period



# Thermal cycling effect





- For the examples used in the study, there was not a strong influence of thermal cycling on the propagation hot spots
- In the case above, the hot spots were located at interconnect to bus bar interface

# Mechanical cycling effect: Results



Sample 3 Mechanical cycling 3 front/rear cycles to 1,500Pa Initial EL & IR images Final EL & IR images **\$FLIR** Max 287 °C Max 161 °C **\$FLIR** 2010-04-22 18:32:11 e=0.96

- Nature and severity of hot spot in this sample changed after repetitive load cycling
- Suggests that this type of stress could be a factor in perturbing the extent of hot spots
- Dependant on weather conditions including local wind and snow conditions
- This could take many years in the field

# Simulated rear side damage at high voltages





Isolated structure with metal probe at -1000V +ve to output cables Current limit: 1A

Sensor measures the distance to the back sheet: 0 to 20mm





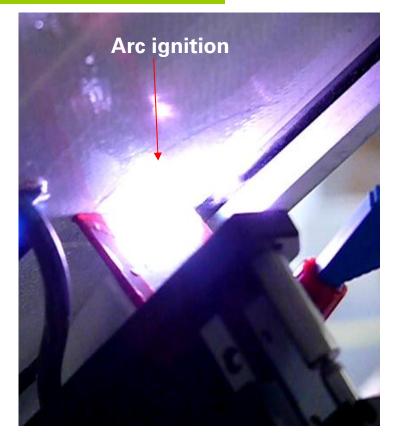
Pressure applied to front of glass to generate deflection



# Simulated back sheet damage Arc initiation







- •Flash over occurred when the probe was in close proximity (<2mm) or direct contact
- •Flash over occurred in dry environments but the presence of water greatly increased the chance for occurrence
- For these conditions, flash over was detected at voltages of 300V or higher
- •<u>Undamaged back sheets</u> did not lead to leakage current or arc initiation

#### Summary



- Many different failure modes can create a hot spots not just p-n junction effects from shading
- A study between BP Solar, Fraunhofer Institute, and VDE examined 28 modules with examples of hot spots
- Broken cells were present but the most common root cause was resistive heating due to defective solder joints
- Maximum temperature measured was 343°C, however the heating effect on the adjacent wooden structure was low
- This is due to the small physical size of the hot spot and low energy dissipation
- Stress testing showed a greater effect from mechanical cycling compared to thermal cycling
- However, this did not significantly increase the hot spot temperature
- By far the biggest risk for secondary damage from hot spots is if their source is a DC arc
- This was demonstrated by simulated back sheet damage at high voltage